

Title (en)

Cu-Ni-Si-Co COPPER ALLOY FOR ELECTRONIC MATERIAL AND PROCESS FOR PRODUCING SAME

Title (de)

CU-NI-SI-CO KUPFERLEGIERUNG FÜR EIN ELEKTRONISCHES MATERIAL UND HERSTELLUNGSVERFAHREN DAFÜR

Title (fr)

CU-NI-SI-CO ALLIAGE DE CUIVRE POUR MATÉRIEL ÉLECTRONIQUE ET SON PROCÉDÉ DE PRODUCTION

Publication

**EP 2484787 B1 20150107 (EN)**

Application

**EP 09849834 A 20090928**

Priority

JP 2009066794 W 20090928

Abstract (en)

[origin: EP2484787A1] A Cu-Ni-Si-Co alloy which has mechanical and electrical properties that render the alloy suitable for use as a copper alloy for electronic materials and which has even mechanical properties. The copper alloy for electronic materials contains 1.0-2.5 mass% nickel, 0.5-2.5 mass% cobalt, and 0.3-1.2 mass% silicon, with the remainder being copper and incidental impurities, and has an average crystal-grain diameter of 15-30 [ $\mu$ ]m, the average of differences between maximum crystal-grain diameter and minimum crystal-grain diameter for respective fields of view each having an area of 0.5 mm<sup>2</sup> being 10 [ $\mu$ ]m or smaller.

IPC 8 full level

**C22C 9/06** (2006.01); **C22F 1/00** (2006.01); **C22F 1/08** (2006.01)

CPC (source: EP KR)

**C22C 9/00** (2013.01 - KR); **C22C 9/06** (2013.01 - EP KR); **C22F 1/08** (2013.01 - EP KR)

Cited by

JP2017210674A

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO SE SI SK SM TR

DOCDB simple family (publication)

**EP 2484787 A1 20120808**; **EP 2484787 A4 20130605**; **EP 2484787 B1 20150107**; CN 102549180 A 20120704; JP 5506806 B2 20140528; JP WO2011036804 A1 20130214; KR 20120054099 A 20120529; WO 2011036804 A1 20110331

DOCDB simple family (application)

**EP 09849834 A 20090928**; CN 200980161688 A 20090928; JP 2009066794 W 20090928; JP 2011532878 A 20090928; KR 20127009709 A 20090928